

ABSTRACT OF THE DISCLOSURE

This invention is made on the basis of the novel findings that when, after pulverization and coating film peeling, pulverized pieces to which the coating film not peeled by the coating film peeling adheres and pulverized pieces having no coating film adhered are separated, a substantial coating film removal ratio effectively increases. In this invention, pulverized pieces obtained upon pulverization of coated resin molded products and coating film peeling of pulverized pieces are prepared. The presence/absence of adhesion of the coating film is sensed and determined for each individual pulverized piece. On the basis of the determination result, a pulverized piece having the coating film adhered is separated from pulverized pieces having no coating film adhered. After the separation, molding is performed by using the pulverized pieces having no coating film adhered. This makes it possible to effectively increase the coating film removal ratio within a short time period without taking a long time in the coating film peeling/separation process, and increase the material yield.